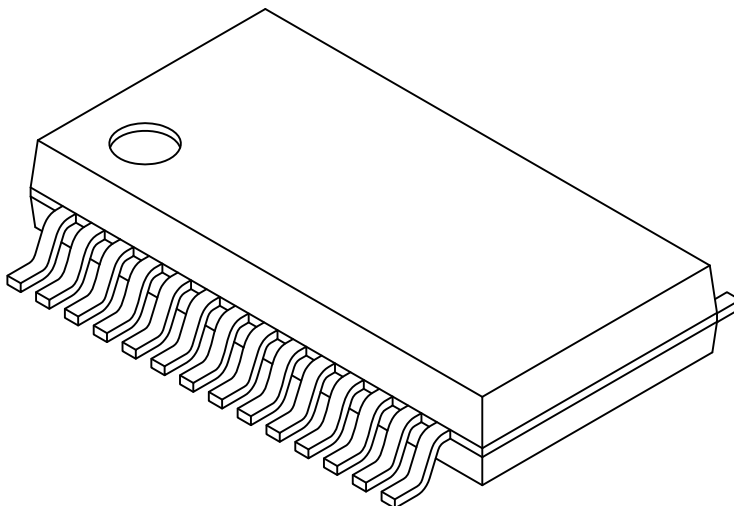


## 28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		28		
Pitch	e		0.65 BSC		
Overall Height	A		-	-	2.00
Molded Package Thickness	A2		1.65	1.75	1.85
Standoff	A1		0.05	-	-
Overall Width	E		7.40	7.80	8.20
Molded Package Width	E1		5.00	5.30	5.60
Overall Length	D		9.90	10.20	10.50
Foot Length	L		0.55	0.75	0.95
Footprint	L1		1.25 REF		
Lead Thickness	c		0.09	-	0.25
Foot Angle	$\varphi$		0°	4°	8°
Lead Width	b		0.22	-	0.38

### Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.